

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YONGFENG GAO	06/25/2019
SHENGPING MAO	06/25/2019
LIANGCHEN YE	06/25/2019
SHAOQING XIANG	06/25/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	HESAI PHOTONICS TECHNOLOGY CO., LTD.
<b>Street Address:</b>	FLOOR 9, BUILDING L2-B, HONGQIAO WORLD CENTRE
<b>Internal Address:</b>	1588 ZHUGUANG ROAD
<b>City:</b>	SHANGHAI
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	201702
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	16738242
<b>CORRESPONDENCE DATA</b>	
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<b>Phone:</b>	6504615211
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<b>ATTORNEY DOCKET NUMBER:</b>	54312-705.302
<b>NAME OF SUBMITTER:</b>	CHRISTINE RICKS
<b>SIGNATURE:</b>	/Christine Ricks/
<b>DATE SIGNED:</b>	02/19/2020
<b>Total Attachments: 1</b>	
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## PATENT ASSIGNMENT

Docket Number 54312-705.301

WHEREAS, the undersigned:

1. GAO, Yongfeng  
Shanghai, China2. MAO, Shengping  
Shanghai, China3. YE, Liangchen  
Shanghai, China4. XIANG, Shaoqing  
Shanghai, China

(hereinafter "Inventor(s)"), have invented certain new and useful improvements in

## SCANNER CONTROL FOR LIDAR SYSTEMS

☒ for which application serial number 16/444,990 was filed on June 18, 2019 in the United States Patent and Trademark Office;

(hereinafter, "Application(s)"). The term "Application(s)" also includes all patent applications that share or claim priority to or from the above application(s).

WHEREAS, Hesai Photonics Technology Co., Ltd., a Company formed in China, having a place of business at Floor 10, Building L2-B, Hongqiao World Centre, 1588 Zhubei Road, Shanghai, 201702, China, (hereinafter "Assignee"), is desirous of acquiring the entire right, title and interest in and to said Application(s), and the inventions disclosed therein, and in and to all embodiments of the inventions, heretofore conceived, made or discovered, whether jointly or severally, by said Inventor(s) (hereinafter collectively referred to as "Inventions"), and in and to any and all patents, inventor's certificates and other forms of protection thereon granted in the United States, foreign countries, or under any international convention, agreement, protocol, or treaty, including those filed under the Paris Convention for the Protection of Industrial Property, The Patent Cooperation Treaty or otherwise (hereinafter "Patent(s)").

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Inventor(s) to have been received in full from said Assignee:

1. Said Inventor(s) do hereby sell, assign, transfer and convey unto said Assignee the entire right, title and interest (a) in and to said Inventions; (b) in and to said Applications, including the right to claim priority to and from said Application(s); (c) in and to each and every application that is a divisional, substitution, continuation, or continuation-in-part of any of said Application(s); (d) in and to said Patent(s) and each and every patent issuing or reissuing from any of the foregoing; (e) in and to each and every reissue, reexamination, renewal or extension of any kind of any of the foregoing; and (f) in and to each and every patent and application filed outside the United States and corresponding to any of the foregoing.

2. Said Inventor(s) hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States, foreign countries, or under any international convention, agreement, protocol, or treaty. Such cooperation by said Inventor(s) shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any applications covering said Inventions; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Inventions; (d) for filing and prosecuting applications for reissuance of any said Patent(s); (e) for interference or other priority proceedings involving said Inventions; and (f) for legal proceedings involving said Inventions and any applications therefor and any Patent(s) granted thereon, including without limitation reissues and reexaminations, opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that reasonable expenses incurred by said Inventor(s) in providing such cooperation shall be paid for by said Assignee.

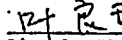
3. The terms and covenants of this assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventor(s), their respective heirs, legal representatives and assigns.

4. Said Inventor(s) hereby warrant, represent and covenant that said Inventor(s) have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

5. Said Inventor(s) hereby request that any Patent(s) issuing in the United States, foreign countries, or under any international convention, agreement, protocol, or treaty, be issued in the name of the Assignee, or its successors and assigns, for the sole use of said Assignee, its successors, legal representatives and assigns.

6. This instrument will be interpreted and construed in accordance with the laws of China, without regard to conflict of law principles. If any provision of this instrument is found to be illegal or unenforceable, the other provisions shall remain effective and enforceable to the greatest extent permitted by law. This instrument may be executed in counterparts, each of which is deemed an original, but all of which together constitute one and the same agreement.

IN WITNESS WHEREOF, said Inventor(s) have executed and delivered this instrument to said Assignee as of the dates written below:

Date: 2019-06-25  
Yongfeng GaoDate: 2019-06-25  
Shengping MaoDate: 2019-06-25  
Liangchen YeDate: 2019-06-25  
Shaoqing Xiang

RECEIVED AND AGREED TO BY ASSIGNEE:

Hesai Photonics Technology Co., Ltd.

Date: 2019.6.25Signature:   
Name/Title: Kai Sun/Chairman/Chief Scientist